

Bridge Characteristics

Parameter	Rating	Units
Reverse Voltage	100	V
Forward Current	240	mA _{rms}

Description

The CPC7557N is an integrated diode bridge built on Clare's High Voltage SOI technology.

Features

- Monolithic Construction
- Surface Mount Package

Applications

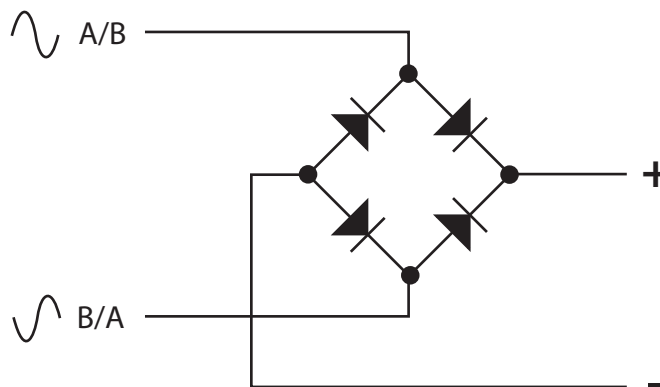
- Telecommunications Protection Clamp
- High Voltage Multiplexer/Switch

Ordering Information

Part	Description
CPC7557N	8-Pin SOIC in Tubes (50/Tube)
CPC7557NTR	8-Pin SOIC Tape & Reel (1000/Reel)

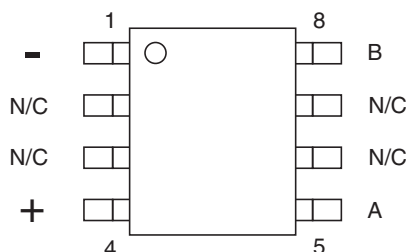


CPC7557N Diagram



1 Specifications

1.1 Package Pinout



1.2 Pin Description

Pin#	Name	Description
1	-	Negative Bridge Output
2	N/C	No Connection
3	N/C	No Connection
4	+	Positive Bridge Output
5	A	Input A
6	N/C	No Connection
7	N/C	No Connection
8	B	Input B

1.3 Absolute Maximum Ratings

Unless Otherwise Specified all electrical ratings are at 25°C

Parameter	Symbol	Minimum	Maximum	Units
Reverse Voltage	V_{RRM}	-	120	V
Diode Forward Current (Average)	I_F	-	250	mA_{rms}
Diode Forward Surge Current	I_{FSM}	-	2	A
Fusing Current	I^2t	-	0.02	A^2s
ESD, Human Body Model	-	-	3	kV
Junction Temperature ¹	T_J	-	+150	°C
Storage Temperature	T_{STG}	-65	+150	°C

¹ Derate package for P_{DISS} 120°C/W.

Absolute maximum ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

1.4 Recommended Operating Conditions

Parameter	Symbol	Minimum	Maximum	Units
Diode Forward Current (Average)	I_F	-	240	mA_{rms}
Reverse Voltage	V_R	-	100	V
Operating Temperature Range	T_A	-40	+125	$^{\circ}\text{C}$
Thermal Impedance	θ_{JA}	120	-	$^{\circ}\text{C/W}$

1.5 General Conditions

Typical values are characteristic of the device at 25°C and are the result of engineering evaluations. They are provided for information purposes only and are not part of the manufacturing testing requirements.

Unless otherwise noted, all electrical specifications are listed for $T_A=25^{\circ}\text{C}$.

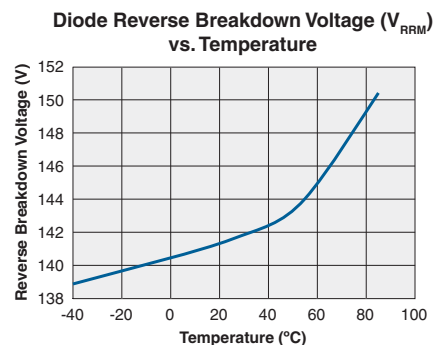
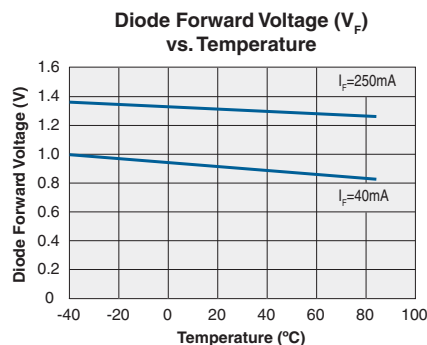
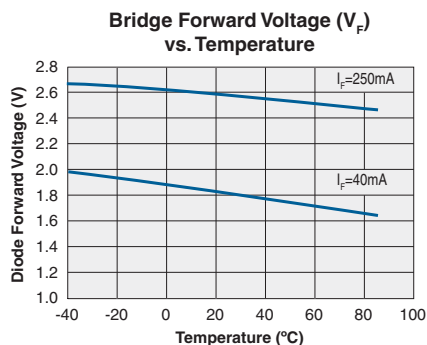
1.6 DC Electrical Characteristics

Parameter	Conditions	Symbol	Minimum	Typical	Maximum	Units
Forward Current	-	I_F	-	-	240	mA_{rms}
Diode Forward Voltage Drop	$I_F = 40\text{mA}$	V_F	0.83	0.91	0.97	V
	$I_F = 250\text{mA}$		1	1.3	1.49	
Reverse Voltage Leakage Current	$V_R=100\text{V}$	I_R	-	-	1	μA

1.7 AC Electrical Characteristics

Parameter	Conditions	Symbol	Minimum	Typical	Maximum	Units
Input Zero Bias Capacitance	$V_+ - V_- = 0\text{V}$ Measured from V_A to V_B	C_{AB}	-	4.4	12	pF
Output Zero Bias Capacitance	$V_A = V_B$ Measured from V_+ to V_-	$C_{+/-}$	-	8.3	20	pF
Bridge Zero Bias Capacitance	$V_+ - V_- = 0\text{V}$ Measured from V_A to $V_{+/-}$ and V_B to $V_{+/-}$	$C_{A/+}, C_{A/-},$ $C_{B/+}, C_{B/-}$	-	8.5	12	pF

2 Typical Performance Data



3 Manufacturing Information

3.1 Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. Clare classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC7557N	MSL 1

3.2 ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

3.3 Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

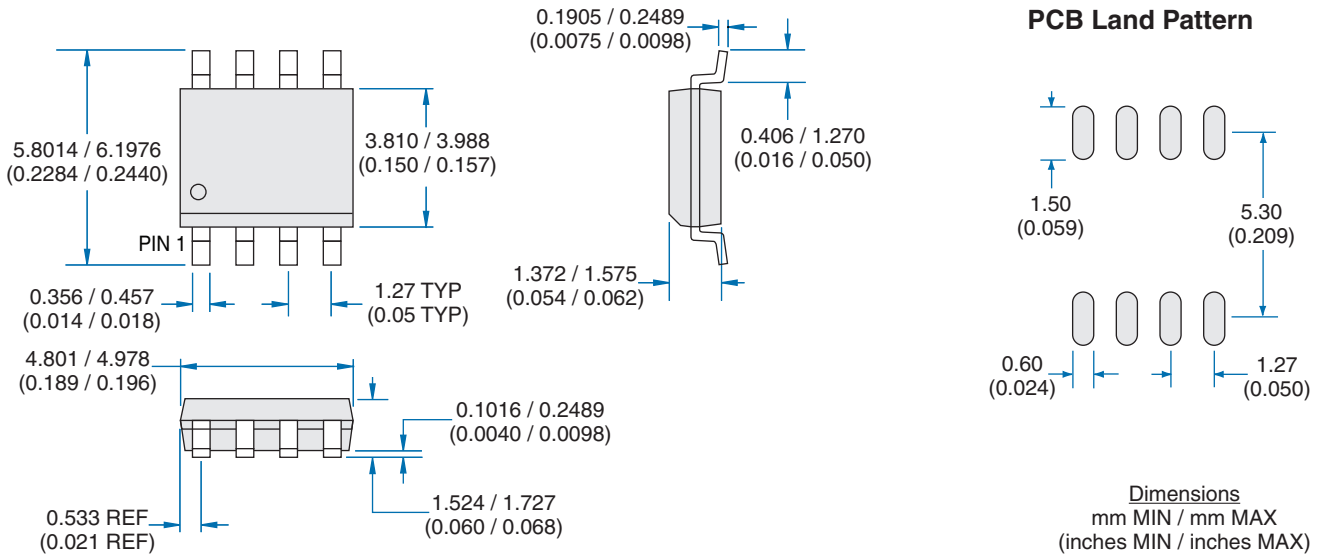
Device	Maximum Temperature x Time
CPC7557N	260°C for 30 seconds

3.4 Board Wash

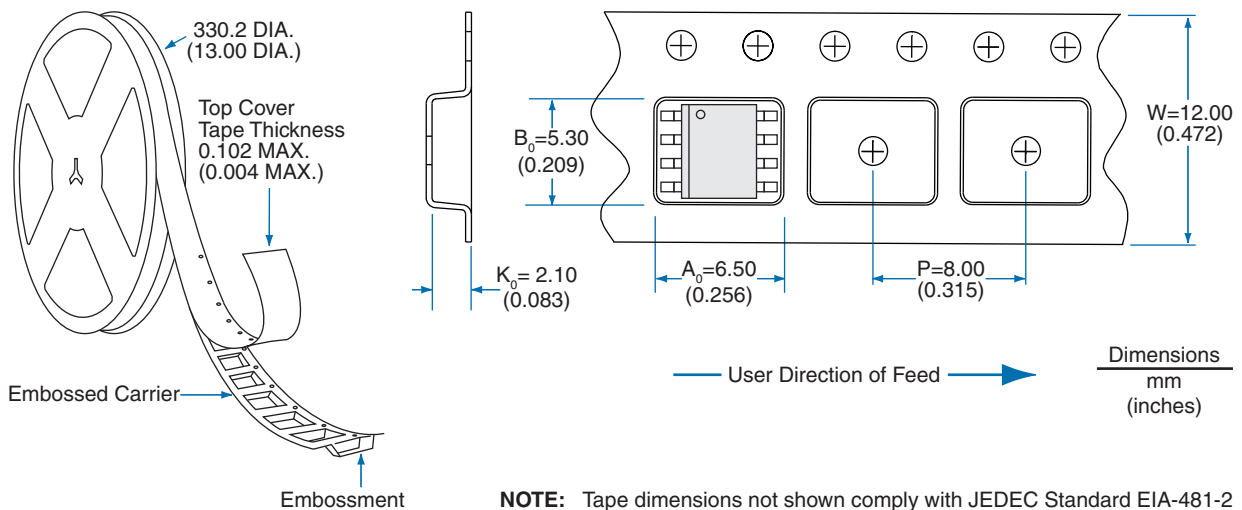
Clare recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. The use of a short drying bake may be necessary if a wash is used after solder reflow processes. Chlorine-based or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



3.5 8-Pin SOIC Package Dimensions



3.6 Tape & Reel Dimensions



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Specification: DS-CPC7557 - R02
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